

## PATENT ASSIGNMENT COVER SHEET

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| <b>SUBMISSION TYPE:</b>      | NEW ASSIGNMENT |
| <b>NATURE OF CONVEYANCE:</b> | ASSIGNMENT     |

**CONVEYING PARTY DATA**

| Name   | Execution Date |
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| SOITEC | 12/09/2019     |

**RECEIVING PARTY DATA**

|                        |  |
|------------------------|--|
| <b>Name:</b>           | SONY SEMICONDUCTOR SOLUTIONS CORPORATION |
| <b>Street Address:</b> | 4-14-1 ASahi-CHO                         |
| <b>City:</b>           | ATSUGI-SHI, KANAGAWA                     |
| <b>State/Country:</b>  | JAPAN                                    |

**PROPERTY NUMBERS Total: 21**

| Property Type  | Number  |
|----------------|---------|
| Patent Number: | 7452745 |
| Patent Number: | 7695996 |
| Patent Number: | 8241942 |
| Patent Number: | 8338294 |
| Patent Number: | 8429960 |
| Patent Number: | 8475612 |
| Patent Number: | 8617925 |
| Patent Number: | 8637995 |
| Patent Number: | 8697493 |
| Patent Number: | 8716105 |
| Patent Number: | 8728863 |
| Patent Number: | 8778773 |
| Patent Number: | 8842945 |
| Patent Number: | 8932938 |
| Patent Number: | 8980688 |
| Patent Number: | 9123631 |
| Patent Number: | 9138980 |
| Patent Number: | 9224704 |
| Patent Number: | 9245836 |
| Patent Number: | 9293448 |
| Patent Number: | 9391011 |

PATENT

**CORRESPONDENCE DATA****Fax Number:** (312)419-9440

*Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.*

**Phone:** 312-380-6504**Email:** dgurfinkel@dennemeyer-law.com**Correspondent Name:** DANIEL M. GURFINKEL**Address Line 1:** DENNEMEYER & ASSOCIATES, LLC**Address Line 2:** 2 NORTH RIVERSIDE PLAZA, SUITE 1500**Address Line 4:** CHICAGO, ILLINOIS 60606

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|--------------------------------|----------------|
| <b>ATTORNEY DOCKET NUMBER:</b> | 30100-10166509 |
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|                           |                    |
|---------------------------|--------------------|
| <b>NAME OF SUBMITTER:</b> | DANIEL M GURFINKEL |
|---------------------------|--------------------|

|                   |                      |
|-------------------|----------------------|
| <b>SIGNATURE:</b> | /daniel m gurfinkel/ |
|-------------------|----------------------|

|                     |            |
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| <b>DATE SIGNED:</b> | 02/04/2020 |
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**Total Attachments: 1**

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UNITED STATES OF AMERICA

ASSIGNMENT OF PATENT

U.S. Patent Nos.: 7452745; 7695996; 8241942; 8338294; 8429960; 8475612; 8617925; 8637995; 8697493; 8716105; 8728863; 8778773; 8842945; 8932938; 8980688; 9123631; 9138980; 9224704; 9245836; 9293448; 9391011

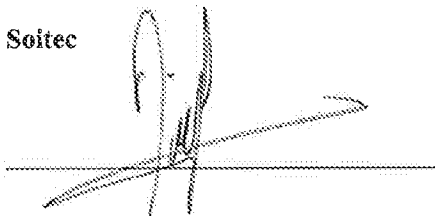
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Assignor further covenants that Assignee will, upon its request and at the expense of Assignee, be provided promptly with all pertinent facts and documents relating to said inventions and said Letters Patents and legal equivalents as may be known and accessible to Assignor and will testify or cause appropriate persons to testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute or have executed, to the best of its ability, and deliver to Assignee or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce any and all of said applications, said inventions and said letters patent and foreign equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

Soitec

09/18/2019  
Date



By: William Nivel  
(Name and Title)

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To be simply signed